

ABSTRACT OF THE DISCLOSURE

A control circuit of a first chip generates control signals for operating a second chip. The first chip and the second chip are manufactured by mutually different processes and packed in a single package. A test control circuit of the first chip inhibits the control
5 signals from being transmitted to the second chip when the first chip is under test. Consequently, the transistors and other components of the second chip are prevented from undergoing stress during a burn-in test on the first chip, for example. As a result, it is possible to conduct a test on the semiconductor device implementing the first chip and second chip whose test conditions are different, with stress applied to the first chip alone.